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HF/1725

Reply Under 37 CFR 1.116
Expedited Procedure - Technology Center 1700

PATENT

In re application of:

TAGUCHI ET AL

Serial No.: 09/642,765

Group Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE FOR REFLOW SOLDERING

Assistant Commissioner for Patents
Washington, D.C. 20231
Box AF

Dear Sir:

RECEIVED
APR 22 2002
TC 1700

An amendment in the above-identified patent application is attached.

[X] No additional claim fee is required.

(Col. 1)		(Col. 2)		(Col. 3)	SMALL ENTITY		OTHER THAN A SMALL ENTITY	
////// ////// ////// ////// //////	CLAIMS REMAINING AFTER AMENDMENT	////// ////// ////// ////// //////	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDIT. FEE	RATE	ADDIT. FEE
TOTAL	* 18	MINUS	** 20	= 0	x 9=	\$	x 18=	\$ 0
INDEP	* 3	MINUS	*** 3	= 0	x 42=	\$	x 84=	\$ 0
FIRST PRESENTATION OF MULT. DEP. CLAIM					+140	\$	+280=	\$
					TOTAL	\$	TOTAL	\$ 0

* If entry in Col. 1 is less than that in Col. 2, write "0" in Col. 3.

** If the highest no. previously paid for IN THIS SPACE is less than 20, write "20" in this space.

*** If the highest no. previously paid for IN THIS SPACE is less than 3, write "3" in this space.

- [] Please charge Deposit Account No. 50-1079 in the amount of \$.
- [X] The Commissioner is authorized to charge any deficiency in the following fees associated with this communication and to credit any excess payment to Deposit Account No. 50-1079. A duplicate copy of this letter is attached.
- [X] Any filing fees pursuant to 37 CFR §1.16 for the presentation of extra claims.
- [X] Any patent application processing fees pursuant to 37 CFR §1.17, including extension of time fees pursuant to 37 CFR §1.17(a)-(d).

Respectfully submitted,



Michael Tobias
Registration Number 32,948

Suite 304
1730 K Street, N.W.
Washington, D.C. 20006
Telephone: (301) 587-6541
Facsimile: (301) 587-6623
Date: April 15, 2002